Title (en)

Method of molding and tentative retention

Title (de)

Verfahren zur Formung und vorläufigen Befestigung

Title (fr)

Procédé de moulage et de retenue provisoire

Publication

EP 1110704 A1 20010627 (EN)

Application

EP 00311368 A 20001219

Priority

JP 36166899 A 19991220

Abstract (en)

A molding and tentatively retaining mold 10 of the invention has a plurality of molds which are relatively movable with respect to a fixed mold, and molds a housing 31 and rear holders 32 and 33, which are respectively independent, in a plurality of cavities formed in cooperation with the fixed mold. When the rear holders 32 and 33 are relatively moved with respect to the housing 31 by a pair of rear-holder tentatively retaining cylinders 19 after molding, and are tentatively retained, the amount of movement of a pair of third movable molds 14 is set to be greater by a predetermined amount than an amount of movement necessary for tentatively retaining the rear holders 32 and 33, and the third movable molds 14 after movement are stopped at the moved positions until a predetermined time elapses. <IMAGE>

IPC 1-7

B29C 69/00; B29C 65/56; B29C 65/00

IPC 8 full level

H01R 43/24 (2006.01); **B29C 45/00** (2006.01); **B29C 45/16** (2006.01); **B29C 45/26** (2006.01); **B29C 45/40** (2006.01); **B29C 65/00** (2006.01); **B29C 65/56** (2006.01); B29L 31/36 (2006.01)

CPC (source: EP US)

B29C 45/006 (2013.01 - EP US); **B29C 65/56** (2013.01 - EP US); **B29C 66/8242** (2013.01 - EP); **B29C 66/83221** (2013.01 - EP US); **B29C 66/9261** (2013.01 - EP US); B29C 66/8226 (2013.01 - EP US); B29C 66/8246 (2013.01 - EP US)

Citation (search report)

[DA] EP 0733463 A2 19960925 - SUMITOMO WIRING SYSTEMS [JP]

Cited by

CN112936934A

Designated contracting state (EPC)

DE FR GB PT

DOCDB simple family (publication)

EP 1110704 A1 20010627; **EP 1110704 B1 20040317**; DE 60009017 D1 20040422; DE 60009017 T2 20041230; JP 2001170974 A 20010626; JP 3625168 B2 20050302; PT 1110704 E 20040730; US 2001011785 A1 20010809; US 6824723 B2 20041130

DOCDB simple family (application)

EP 00311368 A 20001219; DE 60009017 T 20001219; JP 36166899 A 19991220; PT 00311368 T 20001219; US 73967100 A 20001220